

## 2.0\*1.25\*0.8mm Red & Yellow Green Chip LED

### **OSRG0805C1E-0.8T**

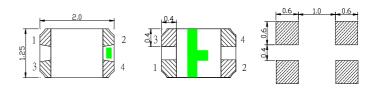
#### **■**Features

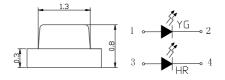
- Bi-Color
- Super high brightness of surface mount LED
- Water Clear Flat Mold
- Compact package outline (LxWxT) of 2.0mm x 1.25mm x 0.8mm
- Compatible to IR reflow soldering.

### **■**Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

#### **Outline Dimension**





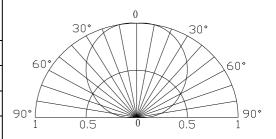
#### Notes:

- 1. All dimensions are in millimeters;
- 2. Tolerance is @0.10 mm unless otherwise noted.

# ■Absolute Maximum Rating

Item	Cromb of	Va	Unit		
nem	Symbol	Red	YG	Unit	
DC Forward Current	$I_F$	30	30	mA	
Pulse Forward Current*	${ m I}_{ m FP}$	100	100	mA	
Reverse Voltage	$V_R$	5	5	V	
Power Dissipation	$P_D$	78	78	mW	
Operating Temperature	Topr	-40	$^{\circ}\!\mathbb{C}$		
Storage Temperature	Tstg	-40~	$^{\circ}\!\mathbb{C}$		
Lead Soldering Temperature	Tsol	260°C	2/10sec	-	

### Directivity



### **■**Electrical -Optical Characteristics

#### (Ta=25°C)

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	Color		$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)		2θ1/2(deg)				
Part Number			Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	
		$I_F=20mA$ $V_R=$		$V_R=5V$	I <sub>F</sub> =20mA									
OCD C0905 C1E 0 9T	Red	R		1.8	2.1	2.6	10	80	150	-	617	625	630	120
OSRG0805C1E-0.8T	Yellow Green	YG		1.8	2.1	2.6	10	30	50	-	565	570	575	120

<sup>\*1</sup> Tolerance of measurements of dominant wavelength is ±1nm

ISO 9001: 2008







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<sup>\*</sup>Pulse width Max 0.1ms, Duty ratio max 1/10

<sup>\*2</sup> Tolerance of measurements of luminous intensity is +15%

<sup>\*3</sup> Tolerance of measurements of forward voltage is ±0.1V



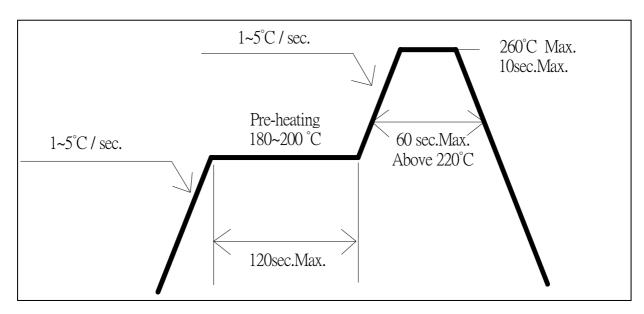
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## **■ Soldering Conditions**

	Reflow Soldering	Hand Soldering				
Pre-Heat	180 ~ 200°C					
Pre-Heat Time	120 sec. Max.					
Peak temperature	260°C Max.	Temperature	350°C Max.			
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.			
Condition	Refer to Temperature-profile		(one time only)			

### • Reflow Soldering Condition(Lead-free Solder)



- \*Recommended soldering conditions vary according to the type of LED
- \*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- \*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

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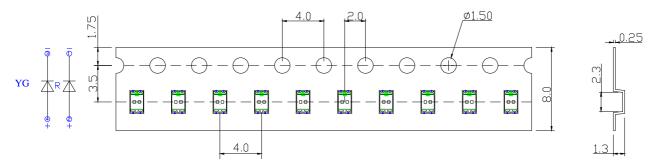


http://www.optosupply.com VER A.1.1

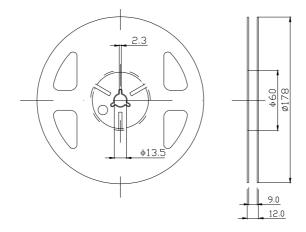


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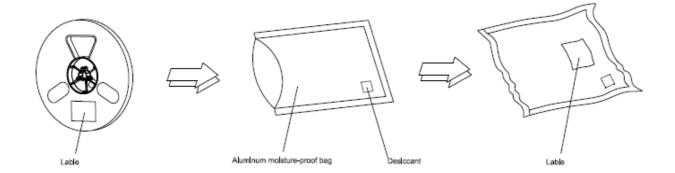
### **TAPING**



## Reel Dimensions



# ■ Moisture Resistant Packaging



#### Notes:

- 1. Unit: mm
- 2. 3000pcs/Reel

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#### **■** Cautions:

- 1. After open the package, the LED's floor life is 1 year under 30° C or less and 60%RH or less (MSL:2).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. ( The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.
- 8. OPTOSUPPLY will not do 4M change without advance consultation.









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